

November 2013

ISL9R1560G2, ISL9R1560P2, ISL9R1560S2, ISL9R1560S3S 15 A, 600 V, STEALTH™ Diode

Features

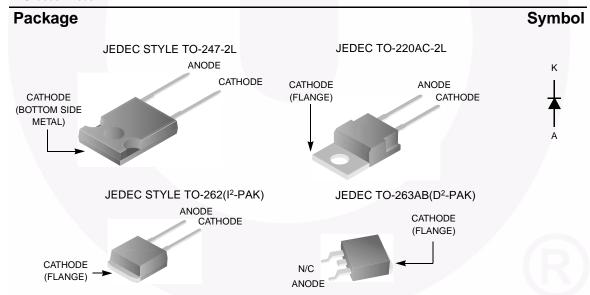
- Stealth Recovery t_{rr} = 29.4 ns (@ I_F = 15 A)
- Max Forward Voltage, V_F = 2.2 V (@ T_C = 25°C)
- 600 V Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- RoHS Compliant

Applications

- SMPS
- · Hard Switched PFC Boost Diode
- · UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

Description

The ISL9R1560G2, ISL9R1560P2, ISL9R1560S2, ISL9R1560S3S is a STEALTH™ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH™ family exhibits low reverse recovery current (I_{rr}) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I_{rr} and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.



Device Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	600	V
V _{RWM}	Working Peak Reverse Voltage	600	V
V _R	DC Blocking Voltage	600	V
I _{F(AV)}	Average Rectified Forward Current (T _C = 145°C)	15	А
I _{FRM}	Repetitive Peak Surge Current (20kHz Square Wave)	30	А
I _{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)	200	Α

Min

Тур

Max

Unit

Symbol	Parameter	Ratings	Unit
P _D	Power Dissipation	150	W
E _{AVL}	Avalanche Energy (1 A, 40 mH)	20	mJ
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 175	°C
T _L T _{PKG}	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s Package Body for 10s, See Techbrief TB334	300 260	°C °C

CAUTION: Stresses above those listed in "Device Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
ISL9R1560G2	ISL9R1560G2	TO-247-2L	Tube	N/A	N/A	30
ISL9R1560P2	ISL9R1560P2	TO-220AC-2L	Tube	N/A	N/A	50
ISL9R1560S2	ISL9R1560S2	TO-262(I ² -PAK)	Tube	N/A	N/A	50
ISL9R1560S3ST	ISL9R1560S3S	TO-263(D ² -PAK)	Reel	13" dia	24mm	800

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Parameter

0	ff State	Characteristics						
	I _R	Instantaneous Reverse Current	V _R = 600 V	$T_C = 25^{\circ}C$	-	-	100	μΑ
				$T_C = 125$ °C	-	-	1.0	mA

On State Characteristics

Symbol

V_{F}	Instantaneous Forward Voltage	I _F = 15 A	$T_C = 25^{\circ}C$	-	1.8	2.2	V
			T _C = 125°C	-	1.65	2.0	V

Dynamic Characteristics

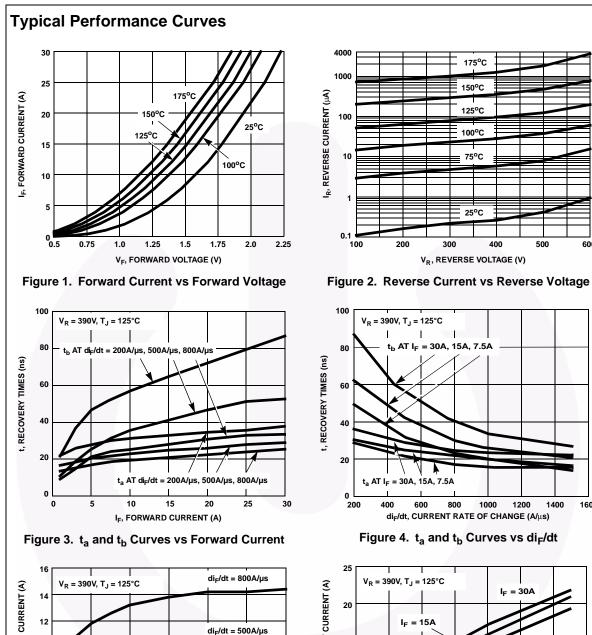
C_{J}	Junction Capacitance	$V_R = 10 \text{ V}, I_F = 0 \text{ A}$	-	62	-	pF

Switching Characteristics

t _{rr}	Reverse Recovery Time	$I_F = 1 \text{ A}, di_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$	-	25	30	ns
		$I_F=15 \text{ A}, di_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$	/ -	35	40	ns
t _{rr}	Reverse Recovery Time	I _F = 15 A,	-	29.4	-	ns
I _{rr}	Reverse Recovery Current	$di_F/dt = 200 \text{ A/}\mu\text{s},$	-	3.5	-	Α
Q _{rr}	Reverse Recovered Charge	V _R = 390 V, T _C = 25°C	-	57	-	nC
t _{rr}	Reverse Recovery Time	I _F = 15 A,	-	90	-	ns
S	Softness Factor (t _b /t _a)	$di_F/dt = 200 \text{ A/}\mu\text{s},$		2.0	-	
I _{rr}	Reverse Recovery Current	V _R = 390 V, T _C = 125°C	-	5.0	-	Α
Q_{rr}	Reverse Recovered Charge	1 C = 123 C	-	275	-	nC
t _{rr}	Reverse Recovery Time	I _F = 15 A,	-	52	-	ns
S	Softness Factor (t _b /t _a)	Softness Factor (t_b/t_a) $di_F/dt = 800 \text{ A/}\mu\text{s},$		1.36	-	
I _{rr}	Reverse Recovery Current	$V_R = 390 \text{ V},$ $T_C = 125^{\circ}\text{C}$	-	13.5	-	Α
Q _{rr}	Reverse Recovered Charge	1 C = 120 C	-	390	-	nC
di _M /dt	Maximum di/dt during t _b		-	800	-	A/µs

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case		-	-	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-247	-	-	30	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-220	-	-	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-262	-	-	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	TO-263	-	-	62	°C/W



, MAX REVERSE RECOVERY CURRENT 8 di_F/dt = 200A/µs 15 25 30 I_F, FORWARD CURRENT (A)

Figure 5. Maximum Reverse Recovery Current vs Forward Current

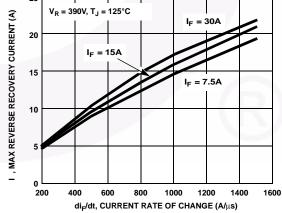
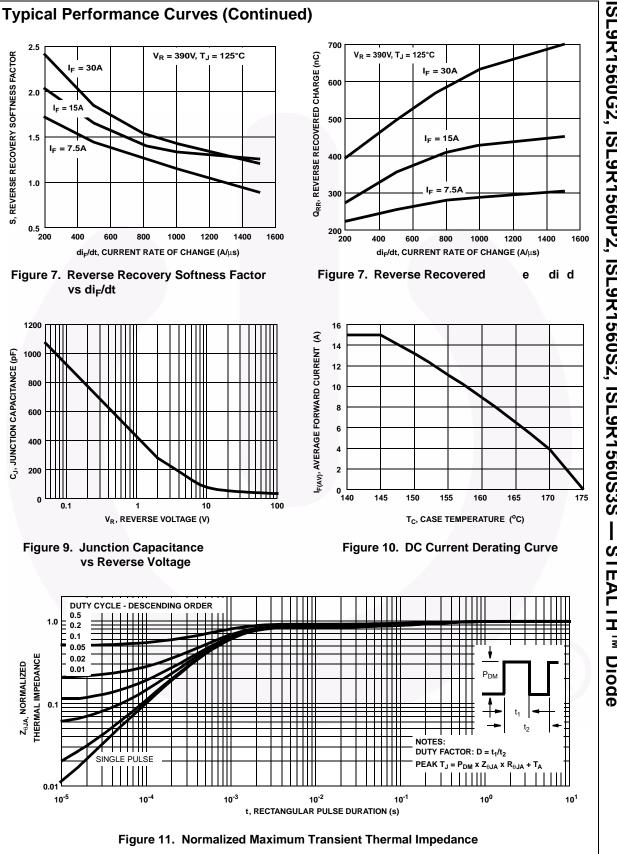
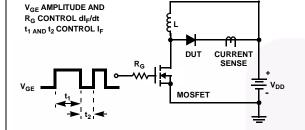


Figure 6. Maximum Reverse Recovery Current vs di_F/dt

10



Test Circuit and Waveforms



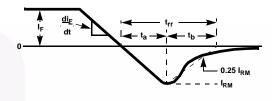
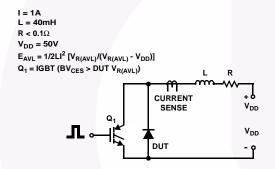


Figure 12. t_{rr} Test Circuit

Figure 13. t_{rr} Waveforms and Definitions



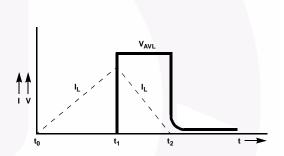


Figure 14. Avalanche Energy Test Circuit

Figure 15. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

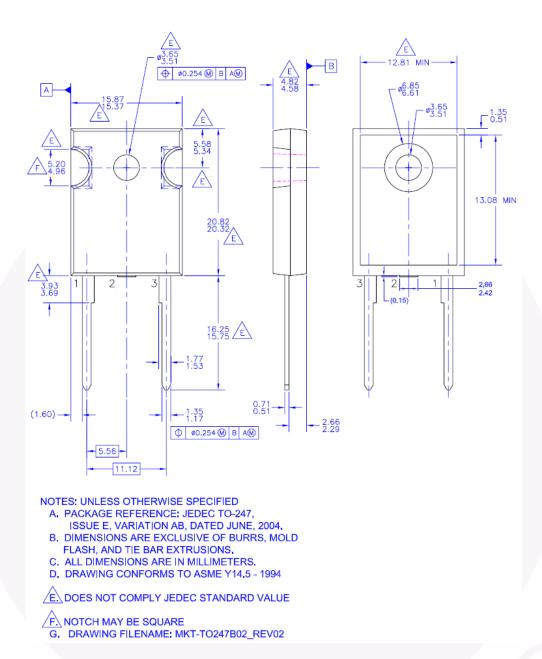


Figure 16. TO-247 2L - TO247, MOLDED, 2LD, JEDEC OPTION AB

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http://www.fairchildsemi.com/package/packageDetails.html?id=PN TO247-002.

Mechanical Dimensions → 0.36M B AM 10.67 9.65 3.43 2.54 13.40 12.19 16.51 9.40 2 1.78 MAX 6.35 14.73 0.61 (1.91)2.54 ◆ 0.38M B AM 5.08 NOTES: UNLESS OTHERWISE SPECIFIED REFERENCE JEDEC, TO-220, ISSUE K, VARIATION AC, DATED APRIL 2002. ALL DIMENSIONS ARE IN MILLIMETERS. A) B) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. C) _ DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1973 D)

Figure 1 . TO-220 2L - 2LD,TO220,JEDEC TO-220 VARIATION AC

E)

IS OPTIONAL

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Mechanical Dimensions

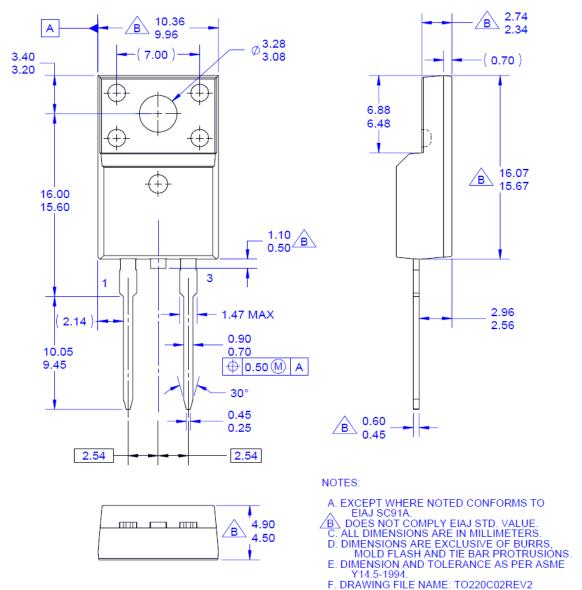


Figure 1 . TO-220F 2L - 2LD; TO220; MOLDED; FULL PACK

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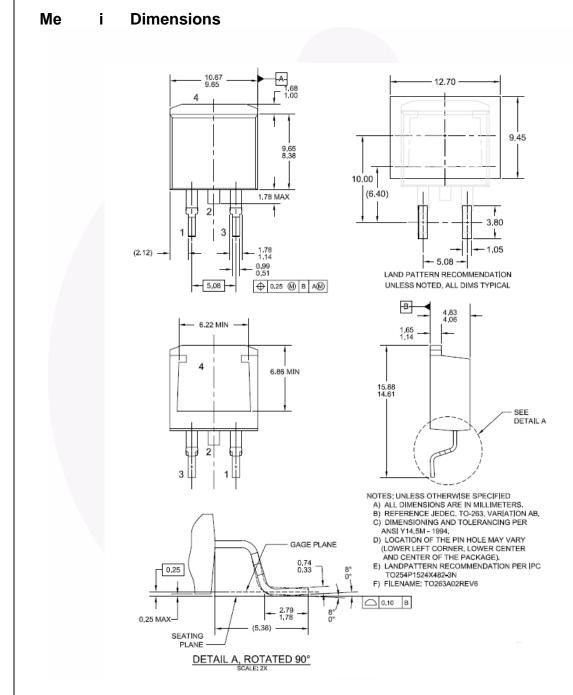


Figure 19. TO-263 2L (D2PAK) - 2LD,TO263, SURFACE MOUNT

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